© Copyright 20	omposition De 2005. IPC, Bannock 21 Pan-American c	burn, Illinois. A	ll rights reserved utions.	under both	This docume level parts, th	ent is a declarat	ion of the su	ibstances v s all lower	vithin the manufactu level materials for v	urer listed which the u	item. Note nanufactu	: if the item is an as rer has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Type   http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and M					lfg Inform	ation		
Supplier Information														
Company name*	Company uni	Company unique ID			Unique ID Authority				Respon	Response Date*				
onsemi										2024-05	2024-05-17			
ontact Name Title - Con			Contact			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards	Product Envir	Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com				
Authorized Representative* Title -			itle - Representative			Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards	Product Envir	Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	umber Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
	NVMFS 1G-YE	NVMFS5C670NLAFT Trench 6 60V I IG-YE		FET		2024-05-17		М	МҮЕ		107.2	mg	Each	
Aanufacturing Proccess Info	rmation													
Terminal Plating / Grid Arra	rid Array Material Terminal Base A		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperatu		emperature	ure Max Time at Peak Tempera		ture Nur	nber of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU A		CU Alloy	1			<b>260</b> C		С	30 seco		seconds 3			
omments														
vel 1 - maximum time at peak temp	erature during so	Idering is 10-3	0 seconds											
or more information regarding mat	terial composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.8	mg	Supplier	Zinc (Zn)	7440-66-6		0.0058	mg
			Supplier	Iron (Fe)	7439-89-6		0.1128	mg
			Supplier	Copper (Cu)	7440-50-8		4.68	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Die	0.73	mg	Supplier	Silicon (Si)	7440-21-3		0.73	mg
Die Attach Solder	2.41	mg	Supplier	Silver (Ag)	7440-22-4		0.0603	mg
			А	Lead (Pb)	7439-92-1	7a	2.2293	mg
			Supplier	Tin (Sn)	7440-31-5		0.1205	mg
Lead Frame	53.97	mg	Supplier	Zinc (Zn)	7440-66-6		0.0648	mg
			Supplier	Iron (Fe)	7439-89-6		1.2683	mg
			Supplier	Copper (Cu)	7440-50-8		52.6208	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0162	mg
Mold Compound-Black	43.54	mg		Epoxy resin	proprietary data		3.2655	mg
			Supplier	Phenolic Resin	Proprietary Data		1.0885	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.2655	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2177	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		35.7028	mg
Plating	1.7	mg	Supplier	Tin (Sn)	7440-31-5		1.7	mg
Wire Bond - Cu	0.05	mg	Supplier	Copper (Cu)	7440-50-8		0.05	mg